are made in the form of splices arranged between the contacts. In a second embodiment, the multilayered switching plate includes electroconductive tracks provided on both sides of each switching layer and are connected together within the limits of each layer by metallized junction openings.

IN THE SPECIFICATION

Please amend the Specification as follows:

On page 2, full paragraph:

A multilayered connection plate on polyimide base comprising layers of polymide film having conductive paths placed on both surfaces of every layer is also known. In order to couple conductors, a metallized through holes 0.1 mm in diameter are formed with every layer. For connecting the layers electrically and mechanically into a multilayered printed circuit plate with the single conductor spreading topology are used specifically formed metallized through holes about 1.5 mm in diameter arranged in the form of matrix with a regular pitch common for all layers which form, after aligning, the matrix of channels piercing the multilayered plate throughout. The conductors and metallized holes are formed by methods of lithography and spraying the metallization with a subsequent galvanic build-up to a required thickness and tinning those places in which should be soldered joints. Assembling the layers into a multilayered structure is performed by soldering the joints between the metallized through holes with the methods of vacuum soldering (Panov E.N. The peculiarities of assembling the specialized LSIC on basic matrix chips. Moscow: "Vysshaya Shkola", 1990. Pp. 31-34).

On page 3, paragraph beginning three lines from the bottom of the page through page 4, eighth line:

The closest technical solution to the present invention by the technical essence and achieved result is a multilayered connection plate based on polyimide, comprising dielectric layers having conductive paths formed on their surfaces, and forming connection layers of the multilayered plate, and also contact nodes made in the form of soldered joints of aligned metallized holes in the connection layers, the nodes performing an inter-layer connection of conductive paths placed both on adjacent and remote connection layers (Panov E.N. The peculiarities of assembling the specialized LSIC on basic matrix chips. Moscow: "Vysshaya Shkola", 1990. Pp. 16-34).